DELKIN DEVICES

M.2 2280 SATA III Industrial Solid State Drive

Engineering Specification

Document Number: 401-0458-00

Revision: B



Product Overview

- Capacity
 - 128GB up to 1TB
- SATA Interface
 - SATA Revision 3.2
 - SATA 1.5Gbps, 3Gbps, and 6Gbps interface
- Flash Interface
 - Flash type: 3D TLC
- Performance
 - Read: up to 550 MB/s
 - Write: up to 500 MB/s
- Power Consumption^{Note1}
 - Active mode: < 1,620 mW
 - Idle mode: < 325 mW
- TBW (Terabytes Written) Note2
 - 835 TBW for 1TB

- MTBF
 - More than 2,000,000 hours
- Features
 - Static and Dynamic Wear Leveling
 - Bad Block Management
 - TRIM
 - NCQ
 - SMART
 - Over-Provisioning
 - Firmware Update Capability
- Low Power Management
 - DIPM/HIPM Mode
 - DEVSLP Mode (Optional)
- Temperature Range
 - Operation: -40°C ~ 85°C
 - Storage: -40°C ~ 85°C
- RoHS compliant

Notes:

- 1. Please see "4.2 Power Consumption" for details.
- 2. Please see "TBW (Terabytes Written)" in Chapter 2" for details.

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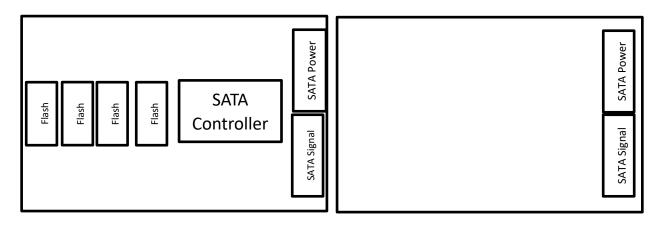
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1. INTRODUCTION

1.1. General Description

Delkin Devices' M.2 2280 Industrial 3D TLC Solid State Drive (SSD) delivers all the advantages of flash disk technology with the performance of the Serial ATA III interface and is fully compliant with the standard Next Generation Form Factor (NGFF) or M.2. Delkin's SSD draws significantly less power compared to traditional hard drives and is ideal for embedded applications. The drive is available in capacities from 128GB to 1TB and can reach speeds up to 550 MB/s read and 500MB/s write (measured by Crystal DiskMark v5.0).

1.2. Product Block Diagram



Front Side Back Side

Figure 1-1 Product Block Diagram

1.3. Flash Management

1.3.1. Error Correction Code (ECC)

Flash memory cells will deteriorate with use, which might generate random bit errors in the stored data. Thus, Delkin's M.2 2280 SSD utilizes a sophisticated LDPC (Low Density Parity Check) ECC algorithm, which can detect and correct errors occur during read process, ensure data been read correctly, as well as protect data from corruption.

1.3.2. Wear Leveling

NAND flash devices can only undergo a limited number of program/erase cycles, and in most cases, the flash media are not used evenly. If some areas are updated more frequently than others, the lifetime of the device would be reduced significantly. Thus, Wear Leveling is applied to extend the lifespan of NAND flash by evenly distributing write and erase cycles across the media.

Delkin utilizes advanced Wear Leveling algorithms, which can efficiently distribute flash usage through the whole flash media area. Moreover, by implementing both dynamic and static Wear Leveling algorithms, the life expectancy of the NAND flash is greatly improved.

1.3.3. Bad Block Management

Bad blocks are blocks that include one or more invalid bits, and their reliability is not guaranteed. Blocks that are identified and marked as bad by the manufacturer are referred to as "Initial Bad Blocks". Bad blocks that are developed during usage of the flash are named "Later Bad Blocks". Delkin implements an efficient bad block management algorithm to detect the factory-produced bad blocks and manages any bad blocks that appear with use. This practice further prevents data being stored into bad blocks and improves data reliability.

1.3.4. TRIM

TRIM is a feature which helps improve the read/write performance and speed of solid-state drives (SSD). Unlike hard disk drives (HDD), SSDs are not able to overwrite existing data, so the available space gradually becomes smaller with each use. With the TRIM command, the operating system can inform the SSD which blocks of data are no longer in use and can be removed permanently. Thus, the SSD will perform an erase action, which prevents unused data from occupying blocks.

1.3.5. SMART

SMART, an acronym for Self-Monitoring, Analysis and Reporting Technology, is an open standard that allows a drive to automatically detect its health and report potential failures. When a failure is recorded by SMART, users can choose to replace the drive to prevent unexpected outage or data loss. Moreover, SMART can inform users of impending failures while there is still time to perform proactive actions, such as copy data to another device.

1.3.6. Over-Provisioning

Over Provisioning refers to the inclusion of extra NAND capacity in a SSD, which is not visible or usable by users. With Over Provisioning, the performance and IOPS (Input/Output Operations per © 2020 | Delkin Devices Inc.

Second) are improved by providing the controller additional space to manage P/E cycles, which enhances the reliability and endurance as well. Moreover, the write amplification of the SSD becomes lower when the controller writes data to the flash.

1.3.7. Firmware Upgrades

Firmware can be considered as a set of instructions on how the device communicates with the host. Firmware can be upgraded when new features are added, compatibility issues are fixed, or read/write performance gets improved, as controlled by the user. It is possible to update firmware in the field, however, there are important factors to consider before attempting a firmware upgrade. Contact Delkin technical support for more information.

1.4. Low Power Management

1.4.1. DIPM/HIPM Mode

SATA interfaces contain two low power management states for power saving: Partial and Slumber modes. In Partial mode, the device must resume full operation within 10 microseconds, whereas in Slumber mode, the device has 10 milliseconds to become fully operational. SATA interfaces allow low power modes to be initiated by Host (HIPM, Host Initiated Power Management) or Device (DIPM, Device Initiated Power Management). As for HIPM, Partial or Slumber mode can be invoked directly by the software. For DIPM, the device will send requests to enter Partial or Slumber mode.

1.5. DEVSLP Mode (Optional)

With the increasing need of aggressive power/battery life, SATA interfaces include a new feature, Device Sleep (DEVSLP) mode, which helps further reduce the power consumption of the device. DEVSLP enables the device to completely power down the device PHY and other sub-systems, making the device reach a new level of lower power operation. The DEVSLP does not specify the exact power level a device can achieve in the DEVSLP mode, but the power usage can be dropped down to 5mW or less..

1.6. Advanced Device Security Features

1.6.1. Secure Erase

Secure Erase is a standard ATA command and will write "0xFF" to all cells, to fully wipe all the data © 2020 | Delkin Devices Inc.

on hard drives and SSDs. When this command is issued, the SSD controller will erase its storage blocks and return to its factory default settings.

1.6.2. Write Protect

When a SSD contains too many bad blocks and data is continuously written in, then the SSD may no longer be usable. Thus, Write Protect is a mechanism to prevent data from being written in and protect the accuracy of data that are already stored in the SSD.

1.7. SSD Lifetime Management

1.7.1. Terabytes Written (TBW)

TBW (Terabytes Written) is a measurement of SSDs' expected lifespan, which represents the amount of data written to the device. To calculate the TBW of a SSD, the following equation is applied:

TBW = [(NAND Endurance) x (SSD Capacity) x (WLE)] / WAF

NAND Endurance: NAND endurance refers to the P/E (Program/Erase) cycle rating of NAND flash, per the manufacturer's specification.

<u>SSD Capacity</u>: The SSD capacity is the specific capacity in total of a SSD.

<u>WLE</u>: Wear Leveling Efficiency (WLE) represents the ratio of the average amount of erases on all the blocks to the erases on any block at maximum.

<u>WAF</u>: Write Amplification Factor (WAF) is a numerical value representing the ratio between the amount of data that a SSD controller writes to the flash and the amount of data that the host's flash controller writes. A better WAF, which is near 1, guarantees better endurance and lower frequency of data written to flash memory.

1.7.2. Thermal Monitor (Optional)

Thermal monitors are devices for measuring temperature, and can be found in SSDs in order to issue warnings when SSDs go beyond a certain temperature. The higher temperature the thermal monitor detects, the more power the SSD consumes, causing the SSD to age quickly. Hence, the processing speed of a SSD should be under control to prevent temperature from exceeding a certain range.

1.8. An Adaptive Approach to Performance Tuning

1.8.1. Throughput

Based on the available space of the disk, Delkin SSD controller will regulate the read/write speed and manage the throughput performance. When significant free space remains, the firmware will continuously perform read/write activity. At this stage, there is still no need to implement garbage collection to allocate and release memory, which will accelerate read/write processing to improve the performance. However, when free space is used up, the controller will slow down the read/write processing, and implement garbage collection to release memory blocks. Hence, read/write performance will become slower.

1.8.2. Predict & Fetch

Normally, when the host tries to read data from the SSD, the SSD will only perform one read action after receiving one command. However, Delkin's controller applies *Predict & Fetch* to improve the read speed. When the host issues sequential read commands to the SSD, the SSD will automatically expect that the following will also be read commands. Thus, before receiving the next command, flash has already prepared the data. Accordingly, this accelerates the data processing time, and the host does not need to wait as long to receive data.

2. PRODUCT SPECIFICATIONS

Capacity

■ From 128GB up to 1TB

• Electrical/Physical Interface

- SATA Interface
 - ♦ Compliant with SATA Revision 3.2
 - ♦ Compatible with SATA 1.5Gbps, 3Gbps and 6Gbps interface
 - Supports power management
 - ♦ Supports expanded register for SATA protocol 48 bit addressing mode

ECC Scheme

■ LDPC (Low Density Parity Check) ECC Algorithm

Supports SMART and TRIM commands

Performance

	Sequential Pe	rformance			
Capacity	CrystalDiskMark				
	Read (MB/s)	Write (MB/s)			
128GB	550	450			
256GB	550	490			
512GB	550	490			
1TB	550	500			

Notes:

- 1. Performance measured with CrystalDiskMark v5.0 x 64 with SATA 6Gbps host.
- 2. Performance may vary with host platform.
- 3. Table above is for reference only.
 - Endurance TBW (Terabytes Written)

Capacity	TBW
128GB	75
256GB	180
512GB	425
1TB	835

NOTES:

1. Many factors affect drive endurance / TBW, including flash configuration, SDR configuration, host platform, usage model, write amplification factor, etc. The figures above are estimates and are not guarantees. The test followed JEDEC219A client endurance workload

Part Numbers

M.2 2280 Industrial TLC SSD Industrial Temperature (-40 to 85°C)

Capacity	Part Number
128GB	MB1HFQQFZ-80000-2
256GB	MB2HFQXFZ-80000-2
512GB	MB5HFQXFZ-80000-2
1TB	MB1TFRAFZ-80000-2

3. ENVIRONMENTAL SPECIFICATIONS

3.1. Environmental Conditions

3.1.1. Temperature and Humidity

- Temperature:
 - ◆ Storage: -40°C to 85°C
 - ◆ Operational: -40°C to 85°C
- Humidity:
 - ◆ RH 95% under 55°C (operational)

3.1.2. Shock & Vibration

- Shock Specification
 - ◆ 1500G, 0.5ms duration
- Vibration Specification
 - ◆ 20Hz ~80Hz/1.52mm displacement, 80Hz~2000Hz / 20G Acceleration, 3 axes

3.1.3. Electrostatic Discharge (ESD)

+/- 4KV

3.1.4. EMI Compliance

• FCC: CISPR22

• CE: EN55022

BSMI 13438

3.2. MTBF

MTBF, an acronym for Mean Time Between Failures, is a measure of a device's reliability. Its value represents the average time between a repair and the next failure. The measure is typically in units of hours. The higher the MTBF value, the higher the reliability of the device. The predicted result of Delkin's M.2 SSD is more than 2,000,000 hours at 0 °C.

3.3. Certification & Compliance

- RoHS
- SATA III (SATA Rev. 3.0)
- Up to ATA/ATAPI-8 (Including S.M.A.R.T)
- WARNING: This product may contain chemicals known to the State of California to cause cancer, birth defects, or other reproductive harm. For more information go to www.p65warnings.ca.gov.

4. ELECTRICAL SPECIFICATIONS

4.1. Supply Voltage

Table 4-1 Supply Voltage

Parameter	Rating
Operating Voltage	3.3V ± 5% (3.14~3.46V)
Rise Time (Max/min)	100ms / 0.1ms
Fall Time (Max/min)	5s / 1ms

4.2. Power Consumption

Table 4-2 Power Consumption

Capacity	Read	Write	Partial	Slumber	Idle		
128GB	1,300	1,350	15	10	300		
256GB	1,350	1,400	15	10	300		
512GB	1,470	1,520	22	15	325		
1TB	1,575	1,620	22	15	325		

Unit: mW

NOTES:

- 1. The average value of power consumption is achieved based on 100% conversion efficiency.
- 2. The measured power voltage is 3.3V.
- 3. Sequential R/W is measured while testing 4000MB sequential R/W 5 times by CrystalDiskMark.
- 4. Power Consumption may differ according to flash configuration, SDR configuration, and host platform.

5. INTERFACE

5.1. Pin Assignment and Descriptions

Table 5-1 defines the signal assignment of the internal NGFF connector for SSD usage, described in the PCI Express M.2 Specification, version 1.0 of the PCI-SIG.

Table 5-1 Pin Assignment and Descriptions for M.2

Pin #	SATA Pin	Description
1	CONFIG_3	Ground
2	3.3V	Supply pin
3	GND	Ground
4	3.3V	Supply pin
5	N/C	No Connect
6	N/C	No Connect
7	N/C	No Connect
8	N/C	No Connect
9	N/C or GND Note	No Connect or Ground
		Status indicators via LED devices that will be provided by the system
10	DAS/DSS# (O) (OD)	Active Low. A pulled-up LED with series current limiting resistor
		should allow for 9mA when On.
11	N/C	No Connect
12	Module Key	
13	Module Key	
14	Module Key	
15	Module Key	
16	Module Key	
17	Module Key	
18	Module Key	
19	Module Key	
20	N/C	No Connect
21	CONFIG_0	Ground
22	N/C	No Connect
23	N/C	No Connect
24	N/C	No Connect
25	N/C	No Connect
26	N/C	No Connect
27	GND	Ground

Pin#	SATA Pin	Description	
28	N/C	No Connect	
29	N/C	No Connect	
30	N/C	No Connect	
31	N/C	No Connect	
32	N/C	No Connect	
33	GND	Ground	
34	N/C	No Connect	
35	N/C	No Connect	
36	N/C	No Connect	
37	N/C	No Connect	
		Device Sleep, Input.	
38	DEVSLP (I) (0/3.3V)	When driven high the host is informing the SSD to enter a low power	
		state	
39	GND	Ground	
40	N/C	No Connect	
41	SATA-B+	SATA differential signals in the SATA specification	
42	N/C	No Connect	
43	SATA-B-	SATA differential signals in the SATA specification	
44	N/C	No Connect	
45	GND	Ground	
46	N/C	No Connect	
47	SATA-A-	SATA differential signals in the SATA specification	
48	N/C	No Connect	
49	SATA-A+	SATA differential signals in the SATA specification	
50	N/C	No Connect	
51	GND	Ground	
52	N/C	No Connect	
53	N/C	No Connect	
54	N/C	No Connect	
55	N/C	No Connect	
56	Reserved for MFG Data	No Connect	
57	GND	Ground	
58	Reserved for MFG Clock	No Connect	
59	Module Key		

Pin #	SATA Pin	Description
60	Module Key	
61	Module Key	
62	Module Key	
63	Module Key	
64	Module Key	
65	Module Key	
66	Module Key	
67	N/C	No Connect
68	SUSCLK (I) (0/3.3V)	No Connect
69	CONFIG_1	Ground
70	3.3V	Supply pin
71	GND	Ground
72	3.3V	Supply pin
73	GND	Ground
74	3.3V	Supply pin
75	CONFIG_2	Ground

NOTE: N/C forSocket 2, and GND for Socket 3.

6. SUPPORTED COMMANDS

6.1. ATA Command List

The following ATA command list table is followed by ATA8-ACS4 SPEC.

Table 6-1 ATA Command List

Op Code	Description	Op (Code		Description
00h	NOP	C9h			Read DMA without Retry
06h	Data Set Management	CAh		h	Write DMA
10h-1Fh	Recalibrate	CBh		h	Write DMA without Retry
20h	Read Sectors		CE	h	Write Multiple FUA EXT
21h	Read Sectors without Retry		E01	h	Standby Immediate
24h	Read Sectors EXT		E11	h	Idle Immediate
25h	Read DMA EXT		E21	h	Standby
27h	Read Native Max Address EXT		E31	h	Idle
29h	Read Multiple EXT		E41	h	Read Buffer
2Fh	Read Log EXT		E51	h	Check Power Mode
30h	Write Sectors		E61	h	Sleep
31h	Write Sectors without Retry		E71	h	Flush Cache
34h	Write Sectors EXT		E81	h	Write Buffer
35h	Write DMA EXT		E91	h	READ BUFFER DMA
37h	Set Native Max Address EXT		EA	h	Flush Cache EXT
38h	CFA Write Sectors Without Erase		EBh		Write Buffer DMA
39h	Write Multiple EXT		EC	h	Identify Device
3Dh	Write DMA FUA EXT		EF	h	Set Features
3Fh	Write Long EXT	EFh		02h	Enable volatile write cache
40h	Read Verify Sectors	EFh		03h	Set transfer mode
41h	Read Verify Sectors without	EFh		05h	Enable the APM feature set
421-	Retry Read Variety Sections EVT	DD1.		1.01.	Englished of CATA footings of
42h	Read Verify Sectors EXT	EFh		10h	Enable use of SATA features et
1 1 lb	Zama EVT	EEL	1.01	02h	Enable DMA Setup FIS Auto-Activate
44h	Zero EXT	EFh	TOII	UZII	optimization
					Enable Device-initiated interface
45h	Write Uncorrectable EXT	EFh	10h	03h	power state (DIPM) transitions
7,311	WITH ORIGINATION OF THE ORIGINAL PROPERTY OF T	151 11	1 011	0311	Enable Software Settings
47h	Read Log DMA EXT	EFh	10h	06h	Preservation
7/11	Read Log DIVIA EAT	171,111	1011	OOH	(SSP)
					(ppr)

Op C	ode	Description	Op C	Op Code		Description
						Enable Device Automatic Partial to
57h		Write Log DMA EXT	EFh	10h 07h		Slumber transitions
601	h	Read FPDMA Queued	EFh	10h 09h		Enable Device Sleep
611		Write FPDMA Queued	EFh		55h	Disable read look-ahead
70h-7	7Fh	Seek	EFh		66h	Disable reverting to power-on defaults
901	h	Execute Device Diagnostic	EFh	82h		Disable volatile write cache
911	h	Initialize Device Parameters	EFh	85h		Disable the APM feature set
921	h	Download Microcode	EFh	90h		Disable use of SATA feature set
						Disable DMA Setup FIS
931	h	Download Microcode DMA	EFh	90h	02h	Auto-Activate optimization
				90h		Disable Device-initiated interface
В0	h	SMART	EFh		03h	power state (DIPM) transitions
						Disable Software Settings
B0h	D0h	SMART READ DATA	EFh	90h	06h	Preservation (SSP)
B0h	D1h	SMART READ ATTRIBUTE	EFh	90h	07h	Disable Device Automatic Partial to
		THRESHOLDS				Slumber transitions
B0h	D2h	SMART ENABLE/DISABILE ATTRIBUTE AUTOSAVE	EFh	90h	09h	Disable Device Sleep
B0h			Ah	Enable read look-ahead		
B0h	D4h	SMART EXECUTE OFF-LINE IMMEDIATE	EFh	Fh CCh		Enable reverting to power-on defaults
B0h	D5h	SMART READ LOG	F1h		1	Security Set Password
B0h	D6h	och SMART WRITE LOG F2h		1	Security Unlock	
B0h	D8h	SMART ENABLE OPERATIONS		F3ł	1	Security Erase Prepare
B0h	D9h	SMART DISABLE OPERATIONS	F4h		1	Security Erase Unit
B0h DAh		SMART RETURN STATUS	F5h		1	Security Freeze Lock

B0h	DBh	SMART ENABLE/DISABILE AUTOMATIC OFF-LINE		F6h	Security Disable Password	
В1	h	Device Configuration	F8h		Read Native Max Address	
B4h		Sanitize	F9h		Set Max Address	
C4	lh	Read Multiple	F9h	01h	SET MAX SET PASSWORD	
C5h		Write Multiple	F9h	02h	SET MAXLOCK	
C6h		Set Multiple Mode	F9h	03h	SET MAX UNLOCK	
C8h		Read DMA	F9h	04h	SET MAX FREEZE LOCIK	

6.2. Identify Device Data

The following table details the sector data returned by the IDENTIFY DEVICE command.

Table 6-2 List of Device Identification

	F: Fixed			
Word	V: Variable	Default Value	Description	
	X: Both			
0	F	0040h	General configuration bit-significant information	
1	Х	*1	Obsolete – Number of logical cylinders	
2	V	C837h	Specific configuration	
3	Х	0010h	Obsolete – Number of logical heads (16)	
4-5	Х	00000000h	Retired	
6	Х	003Fh	Obsolete – Number of logical sectors per logical track (63)	
7-8	V	00000000h	Reserved for assignment by the Compact Flash Association	
9	Х	0000h	Retired	
10-19	F	Varies	Serial number (20 ASCII characters)	
20-21	Х	0000h	Retired	
22	Х	0000h	Obsolete	
23-26	F	Varies	Firmware revision (8 ASCII characters)	
27-46	F	Varies	Model number	
47	F	8010h	7:0- Maximum number of sectors transferred per interrupt on	
			MULTIPLE commands	
48	F	4000h	Trusted Computing feature set options (not support)	
49	F	2F00h	Capabilities	
50	F	4000h	Capabilities	
51-52	Х	000000000h	Obsolete	
53	F	0007h	Words 88 and 70:64 valid	
54	Х	*1	Obsolete – Number of logical cylinders	

55	Х	0010h	Obsolete – Number of logical heads (16)		
56	Х	003Fh	Obsolete – Number of logical sectors per track (63)		
57-58	Х	*2	Obsolete – Current capacity in sectors		
59	F	0110h	Number of sectors transferred per interrupt on MULTIPLE		
			commands		
60-61	F	*3	Maximum number of sector (28bit LBA mode)		
62	Х	0000h	Obsolete		
63	F	0407h	Multi-word DMA modes supported/selected		
64	F	0003h	PIO modes supported		
65	F	0078h	Minimum Multiword DMA transfer cycle time per word		
66	F	0078h	Manufacturer's recommended Multiword DMA transfer cycle time		
67	F	0078h	Minimum PIO transfer cycle time without flow control		
68	F	0078h	Minimum PIO transfer cycle time with IORDY flow control		
69	F	0100h	Additional Supported (support download microcode DMA)		
70	F	0000h	Reserved		
71-74	F	0000000000000000h	Reserved for the IDENTIFY PACKET DEVICE command		
75	F	001Fh	Queue depth		
76	F	670eh	Serial SATA capabilities		
77	F	0084h	Serial ATA Additional Capabilities		
78	F	014Ch	Serial ATA features supported		
79	V	0040h	Serial ATA features enabled		
80	F	07F8h	Major Version Number		
81	F	0000h	Minor Version Number		
82	F	346bh	Command set supported		
83	F	7d09h	Command set supported		
84	F	6063h	Command set/feature supported extension		
85	V	3469h	Command set/feature enabled		
86	V	bc01h	Command set/feature enabled		
87	V	6063h	Command set/feature default		
88	V	003Fh	Ultra DMA Modes		
89	F	0001h	Time required for security erase unit completion		
90	F	001Eh	Time required for Enhanced security erase completion		
91	V	0000h	Current advanced power management value		
92	V	FFFEh	Master Password Revision Code		
93	F	0000h	Hardware reset result. For SATA devices, word 93 shall		
			be set to the value 0000h.		
94	V	0000h	Obsolete		
95	F	0000h	Stream Minimum Request Size		

Word	F: Fixed V: Variable X: Both	Default Value	Description	
96	V	0000h	Streaming Transfer Time – DMA	
97	V	0000h	Streaming Access Latency – DMA and PIO	
98-99	F	0000h	Streaming Performance Granularity	
100-103	V	*4	Maximum user LBA for 48 bit Address feature set	
104	V	0000h	Streaming Transfer Time – PIO	
105	F	0008h	Maximum number of 512-byte blocks per DATA SET	
	·	0000	MANAGEMENT command	
106	F	4000h	Physical sector size/Logical sector size	
107	F	0000h	Inter-seek delay for ISO-7779 acoustic testing in microseconds	
108-111	F	0000000000000000000000h	World Wide Name	
112-115	F	000000000000000000000h	Reserved	
116	V	0000h	Reserved	
117-118	F	0000000h	Words per logical Sector	
119	F	4014h	Supported settings	
120	F	4014h	Command set/Feature Enabled/Supported	
121-126	F	0h	Reserved	
127	F	0h	Obsolete	
128	V	0021h	Security status	
129-140	Х	0h	Vendor specific	
141	Х	0001h	Vendor specific	
142-159	Х	0h	Vendor specific	
160	F	0h	Reserved for CFA	
161-167	Х	0h	Reserved for CFA	
168	F	3h 2.5"	Device Nominal Form Factor	
		4h 1.8"		
		5h Less than 1.8"		
169	F	0001h	DATA SET MANAGEMENT command is supported	
170-173	F	0h	Additional Product Identifier	
174-175		0h	Reserve	
176-205	V	0h	Current media serial number	
206	F	0h	SCT Command Transport	
207-208	F	0h	Reserved	
209	F	4000h	Alignment of logical blocks within a physical block	
210-211	V	0000h	Write-Read-Verify Sector Count Mode 3 (not supported)	
212-213	F	0000h	Write-Read-Verify Sector Count Mode 2 (not supported)	

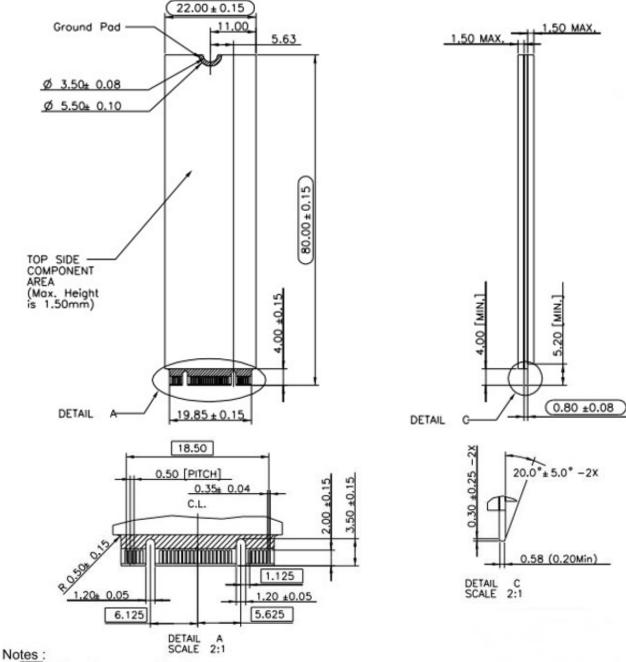
	F: Fixed			
Word	V: Variable	Default Value	Description	
	X: Both			
214-216		0000h	Obsolete	
217	F	0001h	Non-rotating media device	
218	F	0h	Reserved	
219	F	0h	NV Cache relate (not supported)	
220	V	0h	Write read verify feature set current mode	
221		0h	Reserved	
222	F	107Fh	Transport major version number	
223	F	0h	Transport minor version number	
224-229		0h	Reserved	
230-233		0h	Extend number of user addressable sectors	
234		0001h	Minimum number of 512-byte data blocks per DOWNLOAD	
			MICROCODE command for mode 03h	
235		0080h	Maximum number of 512-byte data blocks per DOWNLOAD	
			MICROCODE command for mode 03h	
236-254	F	0h	Reserved	
255	Х	XXA5h	Integrity word (Checksum and Signature)	
		XX is variable		

Table 6-3 List of Device Identification for Each Capacity

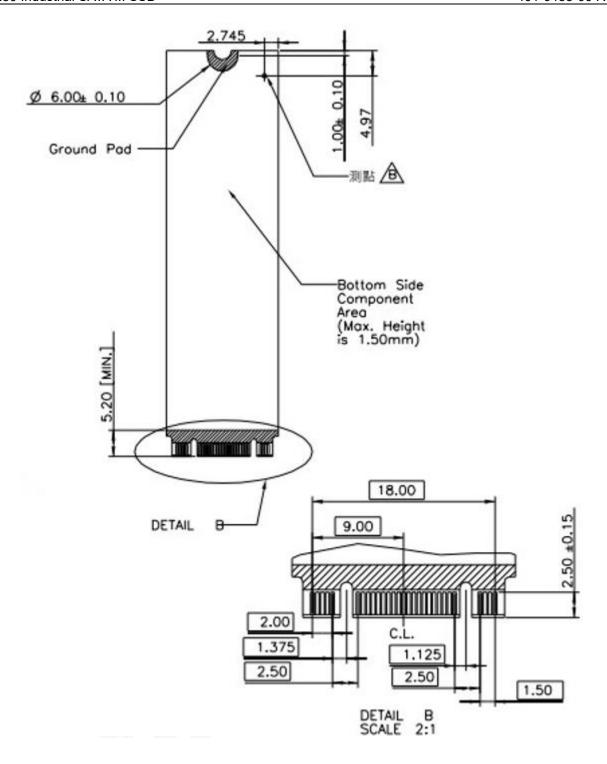
Capacity	*1	*2	*3	*4
(GB)	(Word 1/Word 54)	(Word 57 - 58)	(Word 60 - 61)	(Word 100 - 103)
128	3FFFh	FBFC10h	EE7C2B0h	EE7C2B0h
256	3FFFh	FBFC10h	FFFFFFh	1DCF32B0h
512	3FFFh	FBFC10h	FFFFFFh	3B9E12B0h
1024	3FFFh	FBFC10h	FFFFFFh	773BD2B0h

7. PHYSICAL DIMENSIONS

Dimension: 80mm (L) x 22mm (W) x 1.5mm (H)



- Max Component Height
 Max Component
 Max Component
 Max Component
 Max Component
 Max Component / Signal Vias / Signal Copper / Printing
- 4.General Tolerance ±0.15mm
- is IQC inspection dimension



Unit: mm